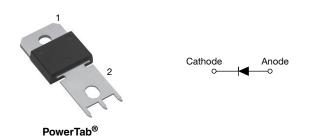


Ultrafast Soft Recovery Diode, 150 A FRED Pt®



PRIMARY CHARACTERISTICS				
I _{F(AV)}	150 A			
V_{R}	200 V			
V _F at I _F	0.79 V			
t _{rr} (typ.)	See recovery table			
T _J max.	175 °C			
Package	PowerTab [®]			
Circuit configuration	Single			

FEATURES

- · Ultrafast recovery time
- 175 °C max. operating junction temperature
- Screw mounting only
- Designed and qualified according to JEDEC®-JESD 47



 Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>





BENEFITS

- Reduced RFI and EMI
- Higher frequency operation
- · Reduced snubbing
- · Reduced parts count

DESCRIPTION / APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems.

The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Cathode to anode voltage	V_R		200	V	
Continuous forward current	I _{F(AV)}	T _C = 116 °C	150		
Single pulse forward current	I _{FSM}	T _C = 25 °C	1600	Α	
Maximum repetitive forward current	I _{FRM}	Square wave, 20 kHz	380		
Operating junction and storage temperatures	T _J , T _{Stg}		-55 to +175	°C	

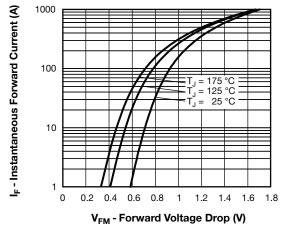
ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	I _R = 100 μA	200	-	-	
Forward voltage V _F	I _F = 150 A	-	0.99	1.13	V	
	I _F = 150 A, T _J = 175 °C	-	0.79	0.90		
Doverne legkage gurrent	1	$V_R = V_R$ rated	-	-	50	μA
Reverse leakage current I _R		$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	-	2	mA
Junction capacitance	C _T	V _R = 200 V	-	180	=	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	3.5	-	nH



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		I _F = 1.0 A, dI _F /dt = 200 A/μs, V _R = 30 V		-	-	45	
Reverse recovery time	t _{rr}	T _J = 25 °C	$I_F = 150 \text{ A}$ $V_R = 160 \text{ V}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$	-	34	-	ns
		T _J = 125 °C		-	58	-	
Peak recovery current I _{RRM}	-	T _J = 25 °C		-	4.5	-	A
	IRRM	T _J = 125 °C		-	9.0	-	
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	87	-	nC
		T _J = 125 °C		-	300	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	IBOL TEST CONDITIONS		TYP.	MAX.	UNITS
Thermal resistance, junction to case	R _{thJC}		-	-	0.35	K/W
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.2	-	T√ VV
Weight			-	-	5.02	g
Weight			-	0.18	-	OZ.
Mounting torque			1.2 (10)	-	2.4 (20)	N ⋅ m (lbf ⋅ in)
Marking device		Case style PowerTab®	150EBU02			

1000



100 T_J = 175 °C 100 125 °C 100 150 200 V_R - Reverse Voltage (V)

Fig. 1 - Maximum Forward Voltage Drop Characteristics

Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

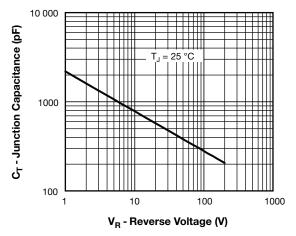


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage



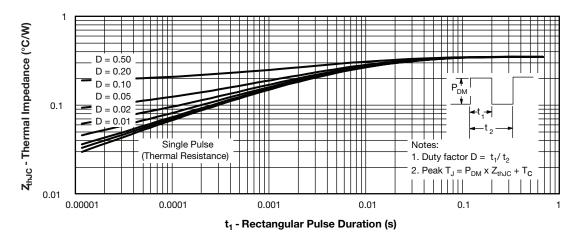


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

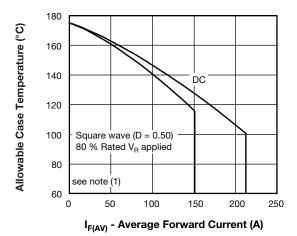


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

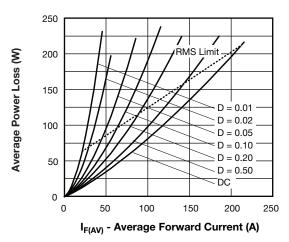


Fig. 6 - Forward Power Loss Characteristics

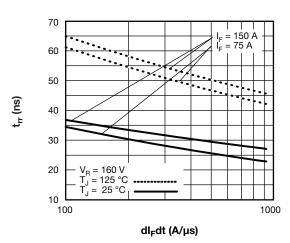


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

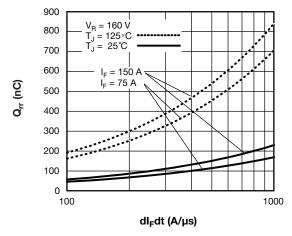


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

⁽¹⁾ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6); Pd_{REV} = inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = 80 % rated V_R

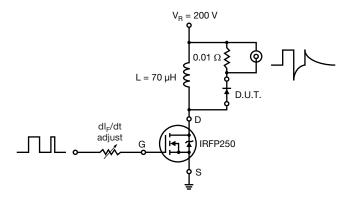
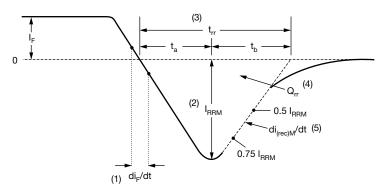


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and $\mathbf{I}_{\mathrm{RRM}}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

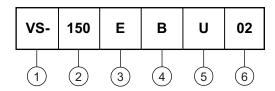
(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (150 = 150 A)

3 - Single diode

4 - PowerTab[®] (ultrafast/hyperfast only)

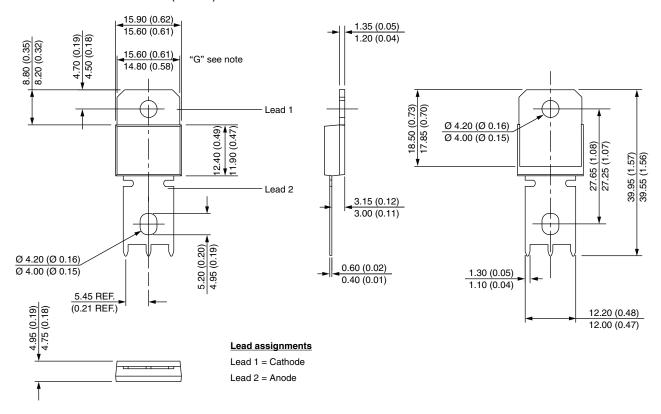
5 - Ultrafast recovery

6 - Voltage rating (02 = 200 V)

LINKS TO RELATED DOCUMENTS					
Dimensions <u>www.vishay.com/doc?95240</u>					
Part marking information	www.vishay.com/doc?95370				
Application note	www.vishay.com/doc?95179				
SPICE model	www.vishay.com/doc?96503				

PowerTab[®]

DIMENSIONS in millimeters (inches)



Note:

Outline conform to JEDEC® TO-275, except for dimension "G" only

Revision: 10-Jun-2021 1 Document Number: 95240

Legal Disclaimer Notice



Vishay

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